

**Amendments to the Specification:**

Please replace the paragraph beginning at page 5, line 12, with the following amended paragraph:

Thus, U.S. Patent No. ~~5,426,406~~ 5,126,102, for example, describes a method for producing a tungsten-copper FGM (functionally graded material) in which a tungsten segment with graded porosity, produced by thermal plasma spraying, for example, is infiltrated with copper.

Please replace the paragraph beginning at page 5, line 22, with the following amended paragraph:

U.S. Patent No. 5,988,488 also describes a production process in which thermal plasma spraying is used to achieve a graded interlayer between the tungsten and copper segments. In contrast to the process described in U.S. Patent No. ~~5,426,406~~ 5,126,102, the copper phase is also separated by thermal plasma spraying, whereby the specific powder blend added contains corresponding proportions of tungsten and copper. A thin metallic film between the tungsten and the FGM promotes adhesion.

Please replace the paragraph beginning at page 6, line 10, with the following amended paragraph:

It can be assumed that the production processes described in both, U.S. Patent No. ~~5,426,406~~ 5,126,102 and U.S. Patent No. 5,988,488 produce laminated parts that exhibit significantly higher resistance to thermally induced cracks. However, the disadvantage of the processes described in these patents is that they are

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Response to Office action 3/24/2006

Response submitted June 22, 2006

complicated and, consequently, the parts produced in the manner described are very expensive. Moreover, due to process engineering constraints, the technologies cited above are applicable to flat-tile structures only. Generally speaking, their use in the production of monoblock geometries is impossible for geometric reasons.